# 2SK1803

## Silicon N-Channel Power F-MOS FET

### ■ Features

- Avalanche capacity guaranteed: EAS > 60mJ
- $\bullet$  V<sub>GSS</sub> =  $\pm 30$ V guaranteed
- $\bullet$  High-speed switching:  $t_f = 80$ ns
- No secondary breakdown

### ■ Applications

- Contactless relay
- Diving circuit for a solenoid
- Driving circuit for a motor
- Control equipment
- Switching power supply

### ■ Absolute Maximum Ratings $(T_C = 25^{\circ}C)$

Parameter		Symbol	Ratings	Unit		
Drain to Source breakdown voltage		V <sub>DSS</sub>	900	V		
Gate to Source voltage		V <sub>GSS</sub>	±30	V		
Drain current	DC	$I_{\mathrm{D}}$	±8	A		
	Pulse	$I_{DP}$	±16	A		
Avalanche energy capacity		EAS*	60	mJ		
Allowable power	$T_C = 25^{\circ}C$	D	100	S W		
dissipation	Ta = 25°C	$P_{\rm D}$	3			
Channel temperature		$T_{ch}$	150	°C		
Storage temperature		$T_{stg}$	-55 to +150	°C		

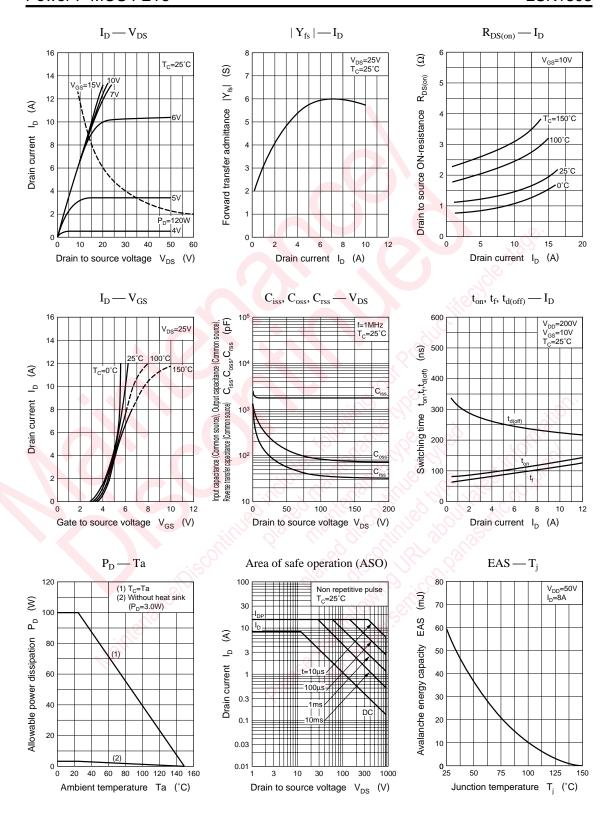
<sup>\*</sup>  $L = 1.9 \text{mH}, I_L = 8 \text{A}, V_{DD} = 50 \text{V}, 1 \text{ pulse}$ 

# unit: mm 15.0±0.3 11.0±0.2 3.2 03.2±0.1 0.6±0.2 1.1±0.1 0.6±0.2 1.1±0.1 1.2 3 1.3 Gate 2. Drain 3. Source TOP-3 Full Pack Package (a)

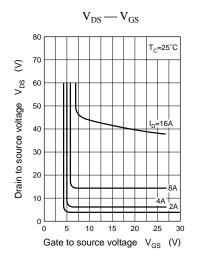
# ■ Electrical Characteristics (T<sub>C</sub> = 25°C)

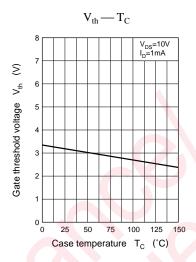
Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	$I_{DSS}$	$V_{DS} = 720V, V_{GS} = 0$	3/1/1		0.1	mA
Gate to Source leakage current	$I_{GSS}$	$V_{GS} = \pm 30V, V_{DS} = 0$			±1	μA
Drain to Source breakdown voltage	$V_{\rm DSS}$	$I_D = 1 \text{mA}, V_{GS} = 0$	900			V
Gate threshold voltage	V <sub>th</sub>	$V_{DS} = 25V$ , $I_D = 1mA$	1		5	V
Drain to Source ON-resistance	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_D = 4A$		1.3	1.7	Ω
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 25V, I_D = 4A$	3	5.5		S
Diode forward voltage	V <sub>DSF</sub>	$I_{DR} = 8A, V_{GS} = 0$			-1.6	V
Input capacitance (Common Source)	C <sub>iss</sub>			1800		pF
Output capacitance (Common Source)	C <sub>oss</sub>	$V_{DS} = 20V, V_{GS} = 0, f = 1MHz$		200		pF
Reverse transfer capacitance (Common Source)	C <sub>rss</sub>			90		pF
Turn-on time	t <sub>on</sub>	V 10V I 44		100		ns
Fall time	t <sub>f</sub>	$V_{GS} = 10V, I_D = 4A$		80		ns
Turn-off time (delay time)	t <sub>d(off)</sub>	$V_{DD} = 200V, R_L = 50\Omega$		250		ns
Thermal resistance between channel and case	R <sub>th(ch-c)</sub>				1.25	°C/W

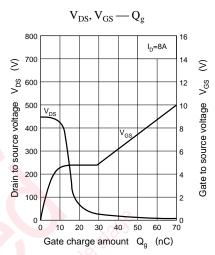
Panasonic 1

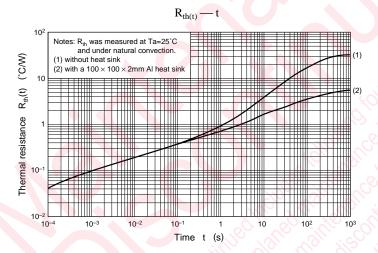


2 Panasonic

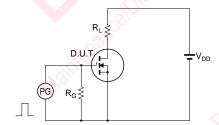




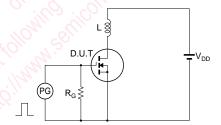




Switching measurement circuit



Avalanche energy capacity test circuit



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